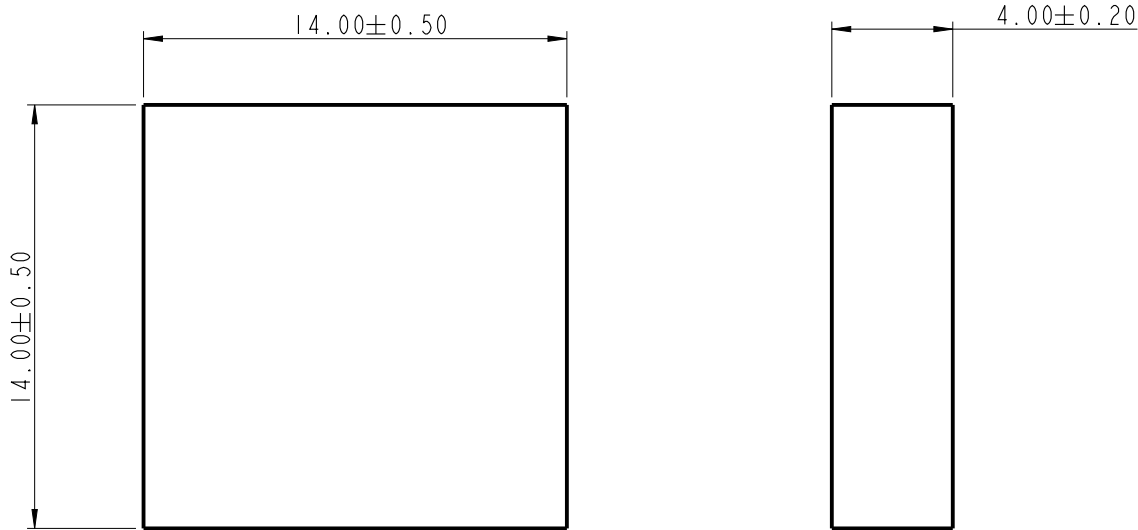


D		C		B		A	
VER.	MARK.	DCR/ECN NO.		DATE	UPDARE DESCRIPTION		SIGNATURE.
00				20181228	First Release		Robin
01				20190315	Update the thermal conductivity.		Robin
02				20210226	Update the tnotes.		Ace



1	Thermal conductivity k (W/mk)	5.0W/m.K (ASTM D5470)
2	Thermal resistance R (°C/W)	0.411@20psi 1.0mm Th=60°C (ASTM 5470 1x1 inch ² test area)
3	Hardness (Shore 00)	45 ASTM 2240
4	Color	Grey
5	With Boron nitride filler	No
6	EMI attenuation	None
7	BSD release film(10 ⁷ -10 ¹¹ Ω)	No
8	UL flammability rating	UL94 V0
9	Supplier PN	TBD
10	Supplier Product Name(series)	Ziitek TIFTM100 50-11S Series

MATERIAL (SPEC.)										SCALE 4.000		 Foxconn Industrial Internet 富士康工业互联网			
FINISH										SHEET 1/1					
SEE NOTES										UNIT mm		PART NAME IC_THERMAL_PAD			
Select Dim. Tol.	A	* B	C	EPS	EPE	BAG	CTN	LABEL	USR	SIZE A3		MODEL T99X171.00	PART NO.	DESIGNED Robin	
0-6	0.05	0.05	0.10					0.20	0.05						
6-30	0.10	0.15	0.20	0.50	0.50	3.00		0.20	0.05						
30-120	0.15	0.20	0.30	0.50	0.50	5.00	2.00	0.25	0.10						
120-300	0.20	0.30	0.40	1.00	1.00	10.00	3.00	0.30	0.15						
300-450	0.25	0.40	0.50	2.00	2.00	15.00	5.00	0.50	0.20						
450-600	0.30	0.50	0.60	3.00	3.00	20.00	5.00	0.80	0.20						
DRAFT TOLERANCE ± 0.2										CRITICAL DIM. MARK *		CUSTOMER MODEL Eagle 4K OTT		CUSTOMER PART NO. N/A	APPROVED Charge